

Title (en)

Apparatus for troubleshooting photoimage plating problems in printed circuit board manufacturing.

Title (de)

Vorrichtung zum Aufsuchen von Störungen bei der Herstellung von phototechnisch realisierten Überzügen auf Leiterplatten.

Title (fr)

Appareil de dépannage pour la fabrication phototechnique de revêtements de plaques à circuits intégrés.

Publication

EP 0395245 B1 19950906 (EN)

Application

EP 90303721 A 19900406

Priority

US 34478289 A 19890428

Abstract (en)

[origin: EP0395245A2] An apparatus and method are disclosed for testing electrodeposition processes used in printed circuit board manufacture. The apparatus, having a photoresist pattern on a test printed circuit board, for use in a Hull Cell to determine efficiency, uniformity, and interactions of the process on the surface of the printed circuit board in order to provide for design rules and process specifications.

IPC 1-7

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IPC 8 full level

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